Materials Declaration

Package	LQFP_INT_HS
Body Size	20 X 20
LeadCount	144
Option	Pb Free

Molding Compound

Item	% of Compound	Weight (g)	PPM
Silica fused	87.0	6.84 E-01	403362
Epoxy resin	7.5	5.90 E-02	34773
Phenol resin	5.5	4.33 E-02	25500

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	99.3	1.28 E-01	75215
Sn	0.3	3.21 E-04	189
Zn	0.3	3.21 E-04	189
Cr	0.2	2.83 E-04	167

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100.0	1.14 E-04	67

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100.0	6.46 E-03	3809

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.9	1.23 E-02	7271

Chip

	% of Chip	Weight (g)	PPM
Si	100.0	1.59 E-02	9348

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag	79.5	1.40 E-03	826
Epoxy resin	15.0	2.64 E-04	156
Aromatic Amine	5.5	9.69 E-05	57

Heat Slug

Item	% of H/S	Weight (g)	PPM
Cu	99.9	7.33 E-01	432069
Ni	0.1	1.31 E-04	77
S	0.002	2.40 E-06	1
Se	0.001	1.33 E-06	1
Tc	0.001	1.33 E-06	1
Bi	0.001	1.33 E-06	1

H/SP Attach

Item	% of H/SP Attach	Weight (g)	PPM
Ag	80.0	9.59 E-03	5651
Epoxy resin	15.0	1.80 E-03	1060
Phenolic resin	3.0	3.60 E-04	212

Package Totals

Weight (g)	PPM
1.70 E+00	1000000

Molding Compound

Item	PPM	Method
Pb	Not Detected	US EPA Method #3052
Cd	Not Detected	US EPA Method #3052
Hg	Not Detected	US EPA Method #3052
Cr+6	Not Detected	US EPA Method #7196A and #3060A
PBB	Not Detected	Analysis was performed by GC/MS
PBDE	Not Detected	Analysis was performed by GC/MS

Die Attach Paste

Item	PPM	Method
Pb	Not Detected	US EPA Method #3050B
Cd	Not Detected	US EPA Method #3050B
Hg	Not Detected	US EPA Method #3052
Cr+6	Not Detected	US EPA Method #3060A
PBB	Not Detected	Analysis was performed by GC/MS
PBDE	Not Detected	Analysis was performed by GC/MS

AST-SQ-G

Note: The information provided in this declaration are true to the best of ADI's knowledge
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information

ADI Proprietary

4/12/06

Materials Declaration

Package	LQFP_INT_HS
Body Size	20 X 20
LeadCount	144
Option	SnPb

Molding Compound

Item	% of Compound	Weight (g)	PPM
Silica fused	87.0	6.84 E-01	403592
Epoxy resin	7.5	5.90 E-02	34792
Phenol resin	5.5	4.33 E-02	25514

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	99.3	1.28 E-01	75258
Sn	0.3	3.21 E-04	190
Zn	0.3	3.21 E-04	190
Cr	0.2	2.83 E-04	167

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100.0	1.14 E-04	67

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85.0	5.49 E-03	3239
Pb	15.0	9.69 E-04	572

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.9	1.23 E-02	7275

Chip

	% of Chip	Weight (g)	PPM
Si	100.0	1.59 E-02	9353

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag	79.5	1.40 E-03	826
Epoxy resin	15.0	2.64 E-04	156
Aromatic Amine	5.5	9.69 E-05	57

Heat Slug

Item	% of H/S	Weight (g)	PPM
Cu	99.9	7.33 E-01	432316
Ni	0.1	1.31 E-04	77
S	0.002	2.40 E-06	1
Se	0.001	1.33 E-06	1
Tc	0.001	1.33 E-06	1
Bi	0.001	1.33 E-06	1

H/SP Attach

Item	% of H/SP Attach	Weight (g)	PPM
Ag	80.0	9.59 E-03	5654
Epoxy resin	15.0	1.80 E-03	1060
Phenolic resin	3.0	3.60 E-04	212

Package Totals

Weight (g)	PPM
1.70 E+00	1000000

Molding Compound

Item	PPM	Method
Pb	Not Detected	US EPA Method #3052
Cd	Not Detected	US EPA Method #3052
Hg	Not Detected	US EPA Method #3052
Cr+6	Not Detected	US EPA Method #7196A and #3060A
PBB	Not Detected	Analysis was performed by GC/MS
PBDE	Not Detected	Analysis was performed by GC/MS

Die Attach Paste

Item	PPM	Method
Pb	Not Detected	US EPA Method #3050B
Cd	Not Detected	US EPA Method #3050B
Hg	Not Detected	US EPA Method #3052
Cr+6	Not Detected	US EPA Method #3060A
PBB	Not Detected	Analysis was performed by GC/MS
PBDE	Not Detected	Analysis was performed by GC/MS

AST-SQ-H

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ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to
any inaccuracy of such information

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4/12/06